TOSHIBA Field Effect Transistor Silicon N Channel MOS Type (U-MOS III)

TPCP8201

Portable Equipment Applications Motor Drive Applications DC-DC Converter Applications

- Lead(Pb)-Free
- Low drain-source ON resistance: RDS (ON) = $38 \text{ m}\Omega$ (typ.)
- High forward transfer admittance: $|Y_{fs}| = 7.0 \text{ S (typ.)}$
- Low leakage current: $IDSS = 10 \mu A (VDS = 30 V)$
- Enhancement mode: $V_{th} = 1.3$ to 2.5 V ($V_{DS} = 10$ V, $I_{D} = 1$ mA)

Absolute Maximum Ratings (Ta = 25°C)

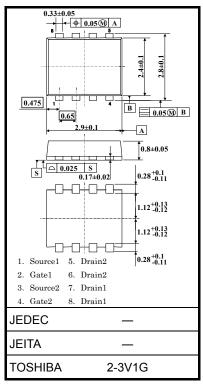
Cł	naracteristics	Symbol	Rating	Unit	
Drain-source v	source voltage V _{DSS} 30		V		
Drain-gate vol	tage (R _{GS} = 20 kΩ)	V_{DGR}	30	V	
Gate-source v	oltage	V _{GSS}	±20	V	
Drain current	DC (Note 1)	ID	4.2	Α	
Diain current	Pulse (Note 1)	I _{DP}	16.8	A	
Drain power dissipation (t = 5 s) (Note 2a)	Single-device operation (Note 3a)	P _{D (1)}	1.48	W	
	Single-device value at dual operation (Note 3b)	P _{D (2)}	1.23		
Drain power dissipation (t = 5 s) (Note 2b)	Single-device operation (Note 3a)	P _{D (1)}	0.58		
	Single-device value at dual operation (Note 3b)	P _{D (2)}	0.36		
Single pulse a	Single pulse avalanche energy (Note 4)		2.86	mJ	
Avalanche cur	rent	I _{AR}	2.1	Α	
Repetitive avalanche energy Single-device value at dual operation (Note 2a, 3b, 5)		E _{AR}	0.12	mJ	
Channel tempo	Channel temperature		150	°C	
Storage temperature range		T _{stg}	-55~150	°C	

Note: For Notes 1 to 6, refer to the next page.

Using continuously under heavy loads (e.g. the application of high temperature/current/voltage and the significant change in temperature, etc.) may cause this product to decrease in the reliability significantly even if the operating conditions (i.e. operating temperature/current/voltage, etc.) are within the absolute maximum ratings. Please design the appropriate reliability upon reviewing the Toshiba Semiconductor Reliability Handbook ("Handling Precautions"/Derating Concept and Methods) and individual reliability data (i.e. reliability test report and estimated failure rate, etc).

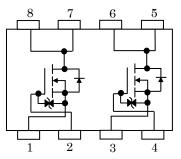
This transistor is an electrostatic-sensitive device. Handle with caution.

Unit: mm

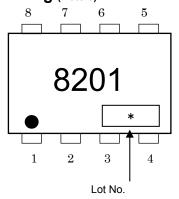


Weight: 0.017 g (typ.)

Circuit Configuration



Marking (Note 6)



FR-4

 $25.4\times25.4\times0.8$

(Unit: mm)

Thermal Characteristics

Characteristics		Symbol	Max	Unit	
Thermal resistance, channel to ambient (t = 5 s) (Note 2a)	Single-device operation (Note 3a)	R _{th (ch-a) (1)}	84.5	°C/W	
	Single-device value at dual operation (Note 3b)	R _{th (ch-a) (2)}	101.6		
Thermal resistance, channel to ambient	Single-device operation (Note 3a)	R _{th (ch-a) (1)}	215.5	°C/W	
(t = 5 s) (Note 2b)	Single-device value at dual operation (Note 3b)	R _{th (ch-a) (2)}	347.2		

- Note 1: The channel temperature should not exceed 150°C during use.
- Note 2: (a) Device mounted on a glass-epoxy board (b) Device mounted on a glass-epoxy board (b)



- Note 3: a) The power dissipation and thermal resistance values shown are for a single device. (During single-device operation, power is only applied to one device.)
 - b) The power dissipation and thermal resistance values shown are for a single device. (During dual operation, power is evenly applied to both devices.)
- Note 4: $V_{DD} = 24 \text{ V}$, $T_{ch} = 25^{\circ}\text{C}$ (initial), L = 0.5 mH, $R_G = 25 \Omega$, $I_{AR} = 2.1 \text{ A}$
- Note 5: Repetitive rating: pulse width limited by maximum channel temperature.
- Note 6: on the lower left of the marking indicates Pin 1.
 - Weekly code (3 digits):



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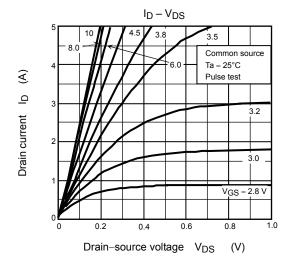
Electrical Characteristics (Ta = 25°C)

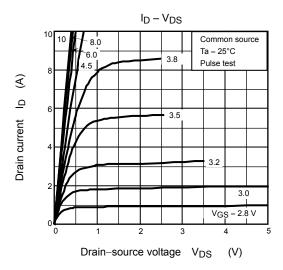
Cha	aracteristics	Symbol	Test Condition	Min	Тур.	Max	Unit
Gate leakage cur	rent	I _{GSS}	V _{GS} = ±16 V, V _{DS} = 0 V	±10		±10	μΑ
Drain cut-off curre	ent	I _{DSS}	V _{DS} = 30 V, V _{GS} = 0 V	10		10	μA
Drain-source brea	akdown	V (BR) DSS	I _D = 10 mA, V _{GS} = 0 V	30	_	_	V
voltage		V (BR) DSX	I_D = 10 mA, V_{GS} = -20 V	15			v
Gate threshold vo	oltage	V _{th}	V _{DS} = 10 V, I _D = 1 mA			2.5	V
Danier and ON		Б	V _{GS} = 4.5 V, I _D = 2.1 A	_	58	77	0
Drain-source ON resistance Forward transfer admittance		R _{DS} (ON)	V _{GS} = 10 V, I _D = 2.1 A	_	38	50	mΩ
Forward transfer admittance		Y _{fs}	V _{DS} = 10 V, I _D = 2.1 A	3.5	7.0	_	S
Input capacitance		C _{iss}	V _{DS} = 10 V, V _{GS} = 0 V, f = 1 MHz	_	470	_	pF
Reverse transfer capacitance		C _{rss}		_	60	_	
Output capacitance		Coss		_	80	_	
Output capacitance Switching time	Rise time	t _r	V _{GS} $\frac{10 \text{ V}}{0 \text{ V}}$ $\frac{\text{ID}}{\text{P}} = 2.1 \text{ A}$ $\frac{\text{O}}{\text{V}}$ $\frac{\text{V}}{\text{OUT}}$ $\frac{\text{V}}{\text{V}}$ $\frac{\text{V}}{\text{DD}} \approx 15 \text{ V}$ Duty $\leq 1\%$, $t_{\text{W}} = 10 \text{ μs}$	_	5.2	_	ns
	Turn-on time	t _{on}		_	8.3	_	
	Fall time	t _f		_	4.0	_	
	Turn-off time	t _{off}		_	22	_	
Total gate charge (gate-source plus gate-drain)		Qg		_	10	_	nC
Gate-source charge 1		Q _{gs1}	$V_{DD} \approx 24 \text{ V}, V_{GS} = 10 \text{ V}, I_D = 4.2 \text{ A}$	_	1.7	_	
Gate-drain ("miller") charge		Q _{gd}		_	2.4	_	

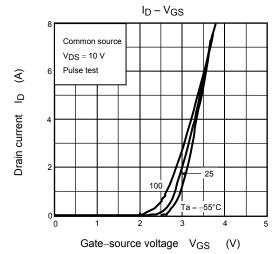
Source-Drain Ratings and Characteristics (Ta = 25°C)

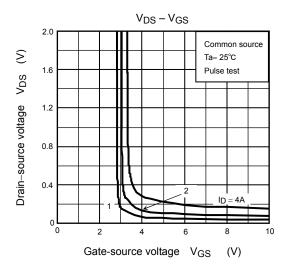
Characterist	ics	Symbol	Test Condition	Min	Тур.	Max	Unit
Drain reverse current	Pulse (Note 1)	I _{DRP}	_	_	_	16.8	Α
Forward voltage (diode)		V _{DSF}	I _{DR} = 4.2 A, V _{GS} = 0 V		_	-1.2	V

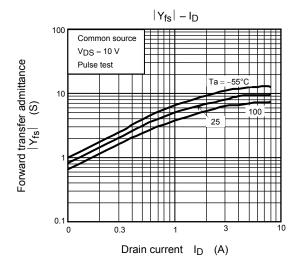
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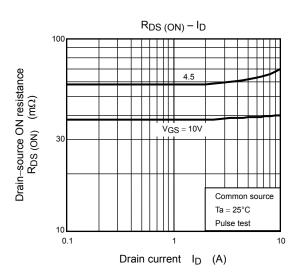


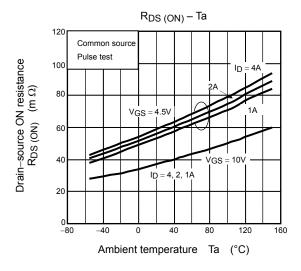


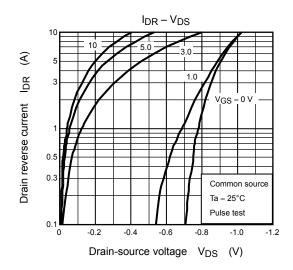


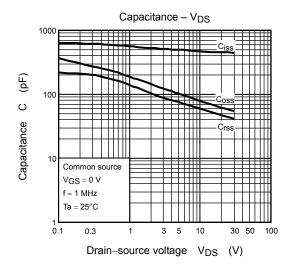


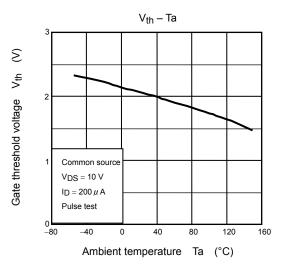


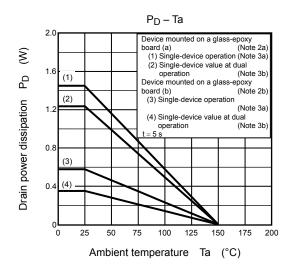


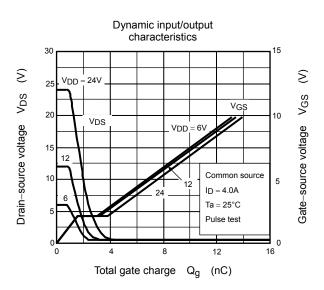


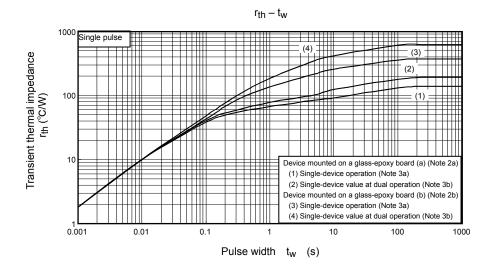


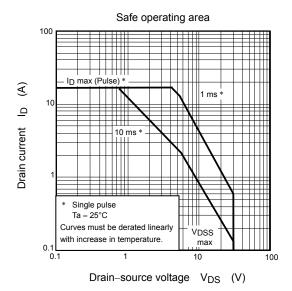












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